

**AMENDMENTS TO THE SPECIFICATION:**

**Please replace the following paragraph on page 1, lines 2-4 with the following  
amended paragraph:**

The present application is a divisional application of a patent application entitled "Mating Assembly for an OEM Device" filed September 30, 2002 and assigned Serial No. 10/260,915. This application relates to subject matter disclosed in a provisional application entitled "Rail and Guide for a Device", filed June 7, 2002 and assigned Serial No. 60/386,977.

**Please replace the following paragraph on page 1, lines 7-8 with the following  
amended paragraph:**

The present invention relates to mating assemblies and, more particularly, to a guide assembly for mechanically supporting and electrically connecting a rail mounted OEM device.

**Please replace the following paragraph on page 3, lines 2-15 with the following  
amended paragraph:**

The present invention relates to guides mounted upon a mechanical substructure for engaging the corresponding rails attached to a an OEM device to be demountably mounted upon the mechanical substructure. The alignment of the OEM device with components of the mechanical substructure is assured through predetermined interconnection and alignment between the guides and the rails. Such alignment permits mating between electromechanical connectors attendant the OEM device and the mechanical substructure. Elements interacting between the guides and the rails assure dissipation of any electrostatic charges and a zero static

potential upon mounting of the OEM device to preclude damage to the electrical components from static electricity. The cooperative engagement between the guides and the rails eliminates the need for manual access to make further mechanical or electrical connections and thereby permit a low profile mechanical packaging enclosure commensurate in size with the OEM device.

It is therefore a primary object of the present invention is to provide a guide and rail assembly for mating and electrically connecting a an OEM device to a mechanical substructure.

**Please replace the following paragraph on page 4, lines 4-8 with the following amended paragraph:**

A further object of the present invention is to provide rails attachable to any OEM device, or a housing therefor, for engagement with guides mounted on the mechanical substructure to which the OEM device is to be mechanically and electrically connected.

A yet further object of the present invention is to provide a method for mating and electrically connecting a an OEM device in alignment with a mechanical substructure.

**Please replace the following paragraph on page 6, lines 12-21 and page 7, lines 1-3 with the following amended paragraph:**

Removably mounted electromechanical devices, such as media storage devices, hard disc drives, etc., may be mounted upon substructure 10 in conformance with the present invention.

Device 20 is illustrated in Figure 1 as being mechanically mounted upon the substructure and electrically connected thereto in conformance with the present invention. Device 22 is illustrated in Figure 1 just prior to mounting same on substructure 10. A pair of rails 30, 32 are attached to each ~~Each of devices 20, 22 has attached directly to it or to a housing 24 for one of devices 20, 22 the device a pair of rails 30, 32.~~ The rails are secured to opposed sides and include ~~including~~ a cross member 34 containing securing means for securing the rail supported device to substructure 10. A pair of screws 36 penetrably engage cross member 34 for threaded engagement with apertured holes in faceplate 56, of which hole 38 is illustrated, to retain device 22 secured to substructure 10. A pair of guides 40, 42 are mounted upon substructure 10 to slidably receive rails 30, 32, respectively to accurately position the rail supported device upon the substructure. An electrical connector 44 is mounted on substructure 10 for mating with a corresponding electrical connector 45 disposed at the rear end of device 22.

**Please replace the following paragraph on page 8, lines 9-15 with the following amended paragraph:**

Each rail may include one or more slots 90, 92[[,]] which slots are coincident with recesses disposed in upstanding leg 82, ~~coincident therewith[[;]] Recess~~ recess 94 aligned with slot 90 is illustrated in Figure 4 [[5]]. A pair of electrostatic discharge contact plates 96, 98 are mechanically attached to substructure 10 and electrically grounded therewith. Each of these plates is lodged within a corresponding one of recesses 94. The primary purpose of plates 96, 98 is that of serving as an electrostatic discharge contacts and is engaged by spring 50 (see Figures 1 and 2) as device 22 is inserted through faceplate 56 of substructure 10.